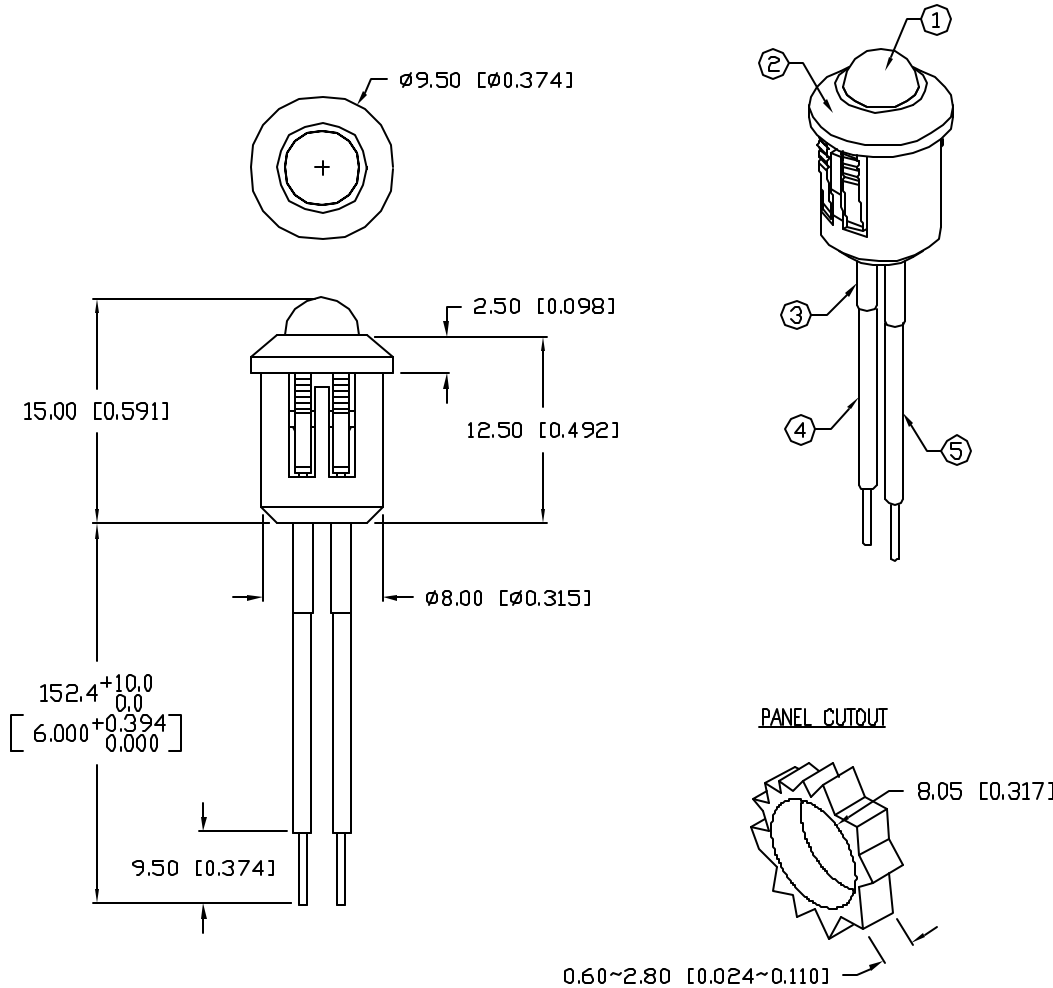


CAUTION: PRESSURE SENSITIVE ASSEMBLY
AVOID APPLYING PRESSURE TO LED
DURING PANEL ASSEMBLY.

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		470		nm	
FORWARD VOLTAGE		3.5	4.0	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		60		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	BLUE				
EPOXY LENS FINISH:	BLUE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX5093USBD, BLUE LED. TRIM LEADS TO 3-4mm.
2. SSH-RTF5010, BLACK HOLDER.
3. LXP-HEATSHRINK-2, (2 PCS.) $1/16" \times 1/2"$.
4. ANODE LEAD: LXP-WST24RDTQC, CUT 160mm LONG, STRIP ENDS 3mm & 9.5mm.
5. CATHODE LEAD: LXP-WST24BLTQC, CUT 160mm LONG, STRIP ENDS 3mm & 9.5mm.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= $\begin{matrix} +\text{DECIMAL PRECISION} \\ -0.00 \end{matrix}$, MAX= $\begin{matrix} +0.00 \\ -\text{DECIMAL PRECISION} \end{matrix}$

REV.

PART NUMBER

SSI-LXR5010USBD150

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T-5mm, 470nm InGaN/SiC BLUE LED PANEL INDICATOR,
BLUE DIFFUSED LENS, 6" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

CHECKED BY:

APPROVED BY:

DATE: 1.5.02

BC

PAGE: 1 OF 1

SCALE: N/A